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**Amendments to the Claims:**

The listing of the claims will replace all the prior versions, and listings, of claims in the applications:

**Listing of Claims:**

Claims 13 – 19 (Cancelled).

Claims 20-25 (New).

Claim 1. (Currently amended) A laminate useful in the manufacture of containers for food products comprising:

a paperboard substrate, ; and

a food contact release layer comprising a physical blend of polymethylpentene and polypropylene bonded to one side of said substrate, the laminate being ovenable and wherein the relative proportion of polymethylpentene and polypropylene in the physical blend are such that the blend of polymethylpentene and polypropylene exhibits softening and melting points greater than softening and melting points of polypropylene.

Claim 2. (Previously presented) The laminate of Claim 1 wherein said food contact release layer comprises a blend of between about 25% and about 75%, by weight, polymethylpentene with the remainder being polypropylene of the blend.

Claim 3. (Original) The laminate of Claim 1 wherein said food contact release layer exhibits a surface tension of between about 24 and about 29 dynes/cm.

Claim 4. (Previously presented) The laminate of Claim 1 wherein said food contact release layer is of a thickness coat weight of between about 3 and about 10 lbs/3000 ft<sup>2</sup>.

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Claim 5. (Original) The laminate of Claim 1 wherein said paperboard is of a basis weight of between about 18 and 320 lbs/3000 ft<sup>2</sup>.

Claim 6. (Previously presented) The laminate of Claim 2 further comprising a tie layer interposed between said paperboard substrate and said food contact release layer.

Claim 7. (Original) The laminate of Claim 6 wherein said tie layer comprises low density polyethylene or linear low density polyethylene, modified by maleic anhydride, vinyl acetate, acrylic acid or methacrylic acid.

Claim 8. (Original) The laminate of Claim 6 wherein the coat weight of said tie layer is between about 1 and about 25 lbs/3000 ft<sup>2</sup>.

Claim 9. (Original) The laminate of Claim 1 wherein said food contact release layer exhibits a surface tension of less than about 40% of the surface tension of water at 20 °C.

Claim 10. (Original) The laminate of Claim 1 wherein said food contact release layer exhibits a surface tension of less than about 75% of the surface tension of starch whereby food products may be baked when disposed in a container formed from the laminate of Claim 1.

Claim 11. (Original) The laminate of Claim 2 and including a grease resistant layer and a tie layer, said tie layer being disposed between said food contact release layer and grease resistant layer.

Claim 12. (Original) The laminate of Claim 1 wherein said food contact release layer is extruded onto said paperboard substrate.

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Claim 20. (New) The laminate of Claim 1 wherein said food contact release layer comprises a blend of between about 50% and about 75%, by weight, polymethylpentene with the remainder being polypropylene of the blend.

Claim 21. (New) The laminate of Claim 2 wherein said food contact release layer comprises a blend of between about 25% and about 75%, by weight, polypropylene with the remainder being polymethylpentene of the blend.

Claim 22. (New) The laminate of Claim 2 wherein said food contact release layer comprises a blend of between about 50% and about 75%, by weight, polypropylene with the remainder being polymethylpentene of the blend.

Claim 23. (New) The laminate of Claim 1 wherein the physical blend of polymethylpentene and polypropylene exhibits softening and melting points greater than 300 °F.

Claim 24. (New) The laminate of Claim 1 wherein the physical blend of polymethylpentene and polypropylene exhibits softening and melting points equal to or greater than 350 °F.

Claim 25. (New) The laminate of Claim 1 wherein the physical blend of polymethylpentene and polypropylene exhibits softening and melting points equal to or greater than 400 °F.